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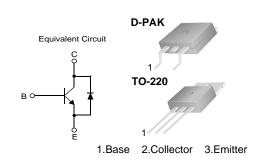


December 2009

KSC5402D/KSC5402DT NPN Silicon Transistor, Planar Silicon Transistor

Features

- High Voltage High Speed Power Switch Application
- Wide Safe Operating Area
- Built-in Free Wheeling Diode
- Suitable for Electronic Ballast Application
- Small Variance in Storage Time
- Two Package Choices; D-PAK or TO-220



Absolute Maximum Ratings T_A =25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CBO}	Collector-Base Voltage	1000	V
V_{CEO}	Collector-Emitter Voltage	450	V
V_{EBO}	Emitter-Base Voltage	12	V
I _C	Collector Current (DC)	2	А
I _{CP}	*Collector Current (Pulse)	5	Α
I _B	Base Current (DC)	1	Α
I _{BP}	*Base Current (Pulse)	2	А
P _C	Power Dissipation(T _C =25°C) : D-PAK* : TO-220	30 50	W W
T _J	Junction Temperature	150	°C
T _{STG}	Storage Temperature	- 65 to 150	°C

^{*} Pulse Test: Pulse Width=5ms, Duty Cycle<10%

Thermal Characteristics T_A=25°C unless otherwise noted

Symbol	Parameter		Rat	Units	
			TO-220	D-PAK	
$R_{ heta JC}$	Thermal Resistance	Junction to Case	2.5	4.17*	°C/W
$R_{\theta JA}$		Junction to Ambient	62.5	50	°C/W
TL	Maximum Lead Temperature for Soldering Purpose ; 1/8" from Case for 5 Seconds		270	270	°C

^{*} Mounted on 1" square PCB (FR4 ro G-10 Material)

Electrical Characteristics T_A =25°C unless otherwise noted

Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Units
BV _{CBO}	Collector-Base Breakdown Voltage	I _C =1mA, I _E =0		1000	1090		V
BV _{CEO}	Collector-Emitter Breakdown Voltage	I _C =5mA, I _B =0	I _C =5mA, I _B =0		525		V
BV _{EBO}	Emitter-Base Breakdown Voltage	I _E =1mA, I _C =0		12	14		V
I _{CES}	Collector Cut-off Current	V _{CES} =1000V, I _{EB} =0	T _A =25°C		0.03	100	μА
			T _A =125°C		1.2	500	μΑ
I _{CEO}	Collector Cut-off Current	V_{CE} =450V, V_{B} =0	T _A =25°C		0.3	100	μΑ
			T _A =125°C		15	500	μΑ
I _{EBO}	Emitter Cut-off Current	V_{EB} =10V, I_{C} =0			0.01	100	μΑ
h _{FE}	DC Current Gain	$V_{CE}=1V$, $I_{C}=0.4A$	T _A =25°C	14	29		
			T _A =125°C	8	17		
		V _{CE} =1V, I _C =1A	T _A =25°C	6	9		
			T _A =125°C	4	6		
V _{CE} (sat)	Collector-Emitter Saturation Voltage	I _C =0.4, I _B =0.04A	T _A =25°C		0.25	0.6	V
			T _A =125°C		0.4	1.0	V
		I _C =1A, I _B =0.2A	T _A =25°C		0.3	0.75	V
			T _A =125°C		0.65	1.2	V
V _{BE} (sat)	Base-Emitter Saturation Voltage	I _C =0.4A, I _B =0.04A	T _A =25°C		0.78	1.0	V
			T _A =125°C		0.65	0.9	V
		I _C =1A, I _B =0.2A	T _A =25°C		0.85	1.1	V
			T _A =125°C		0.75	1.0	V
C _{ib}	Input Capacitance	V _{EB} =8V, I _C =0, f=1MHz			330	500	pF
C _{ob}	Output Capacitance	V _{CB} =10V, I _E =0, f=1MHz			35	100	pF
f _T	Current Gain Bandwidth Product	I _C =0.5A, V _{CE} =10V			11		MHz
V _F	Diode Forward Voltage	I _F =1A	T _A =25°C		0.86	1.5	V
		I _F =0.2A	T _A =25°C		0.75	1.2	V
			T _A =125°C		0.6		V
		I _F =0.4A	T _A =25°C		0.8	1.3	V
		T _A =125			0.65		V

Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Units
t _{fr}	Diode Froward Recvery Time (di/dt=10A/μs)	I _F =0.2A I _F =0.4A I _F =1A			540 520 480		ns ns ns
V _{CE} (DSAT)	Dynamic Saturation Voltage	I _C =0.4A, I _{B1} =40mA	@ 1μs		7.5		V
		V _{CC} =300V	@ 3μs		2.5		V
		I _C =1A, I _{B1} =200mA V _{CC} =300	@ 1μs		11.5		>
			@ 3μs		1.5		V
RESISTIVE	LOAD SWITCHING (D.C ≤ 10%, I	Pulse Width=20μs)					
t _{ON}	Turn On Time	I _C =1A,	T _A =25°C		110	150	ns
		I _{B1} =200mA, I _{B2} =150mA,	T _A =125°C		135		ns
t _{OFF}	Turn Off Time	V _{CC} =300V,	T _A =25°C	0.95		1.25	μS
		$R_L = 300\Omega$	T _A =125°C		1.4		μS
INDUCTIVE	LOAD SWITCHING (V _{CC} =15V)						
t _{STG}	Storage Time	I _C =0.4A, I _{B1} =40mA, I _{B2} =200mA, Vz=300V, L _C =200H	T _A =25°C		0.56	0.65	μS
			T _A =125°C		0.7		μS
t _F	Fall Time		T _A =25°C		60	175	ns
			T _A =125°C		75		ns
t _C	Cross-over Time		T _A =25°C		90	175	ns
			T _A =125°C		90		ns
t _{STG}	Storage Time	I _C =0.8A,	T _A =25°C			2.75	μS
		I _{B1} =160mA, I _{B2} =160mA,	T _A =125°C		3		μS
t _F	Fall Time	Vz=300V,	T _A =25°C		110	175	ns
		L _C =200H	T _A =125°C		180		ns
t_{C}	Cross-over Time		T _A =25°C		125	350	ns
			T _A =125°C		185		ns
t _{STG}	Storage Time	I _C =1A,	T _A =25°C		1.1	1.2	μS
		I _{B1} =200mA, I _{B2} =500mA, V _Z =300V, L _C =200μH	T _A =125°C		1.35		μS
t_{F}	Fall Time		T _A =25°C		105	150	ns
			T _A =125°C		75		ns
t _C	Cross-over Time		T _A =25°C		125	150	ns
			T _A =125°C		100		ns

Typical Performance Characteristics

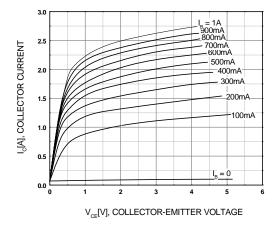


Figure 1. Static Characteristic

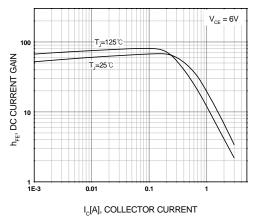


Figure 3. DC current Gain

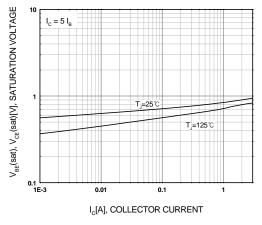


Figure 5. Base-Emitter Saturation Voltage

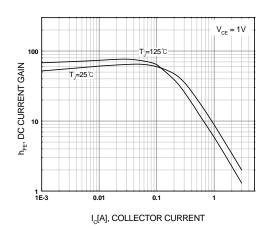


Figure 2. DC current Gain

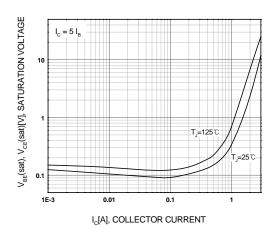


Figure 4. Collector-Emitter Saturation Voltage

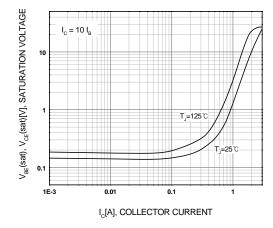


Figure 6. Collector-Emitter Saturation Voltage

Typical Performance Characteristics (Continued)

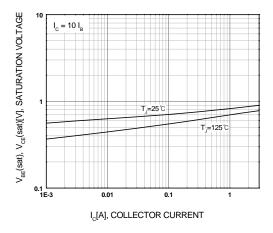


Figure 7. Base-Emitter Saturation Voltage

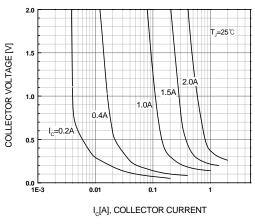


Figure 9. Typical Collector Saturation Region

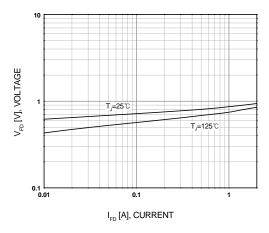


Figure 11. Diode Forward Voltage

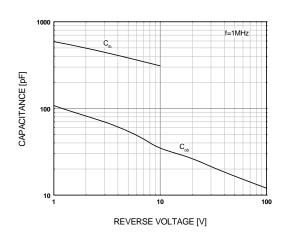


Figure 8. Collector Output Capacitance

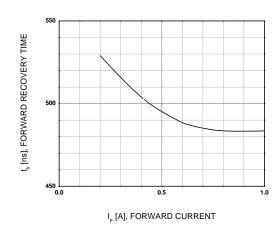


Figure 10. Forward Recovery Time

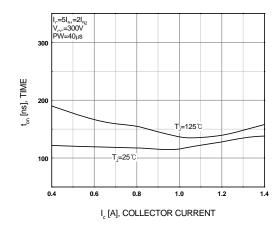


Figure 12. Resistive Switching Time, ton

Typical Performance Characteristics (Continued)

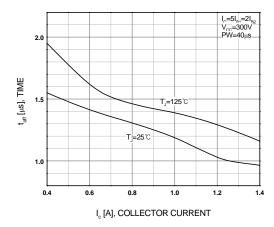


Figure 13. Resistive Switching Time, toff

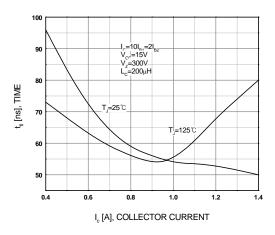


Figure 15. Inductive Switching Time, tfi

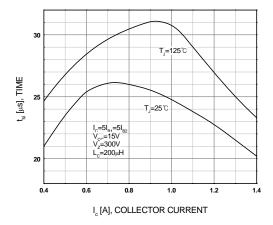


Figure 17. Inductive Switching Time, t_{si}

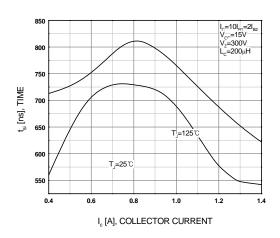


Figure 14. Inductive Switching Time, tsi

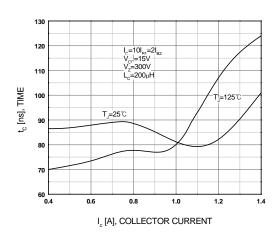


Figure 16. Inductive Switching Time, t_c

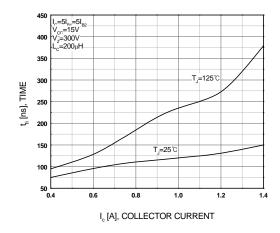


Figure 18. Inductive Switching Time, tfi

Typical Performance Characteristics (Continued)

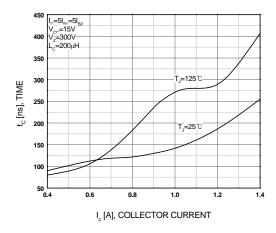


Figure 19. Inductive Switching Time, t_c

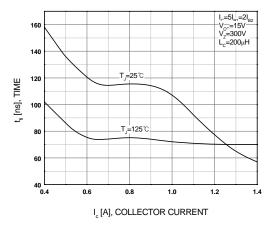


Figure 21. Inductive Switching Time, tfi

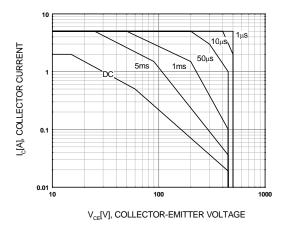


Figure 23. Forward Bias Safe Operating Area

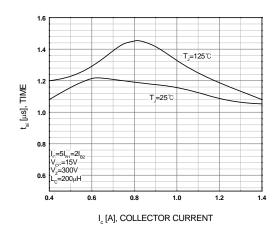


Figure 20. Inductive Switching Time, tsi

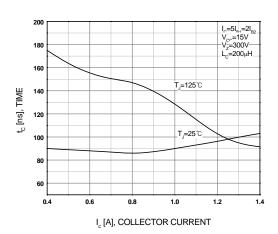


Figure 22. Inductive Switching Time, t_c

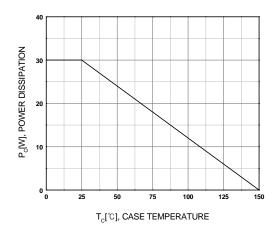
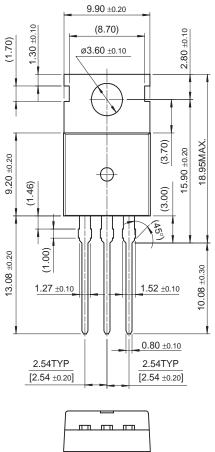
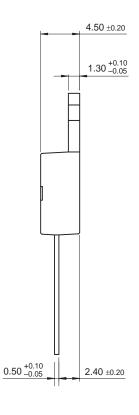


Figure 24. Power Derating

Physical Dimension

TO-220



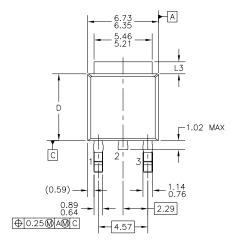


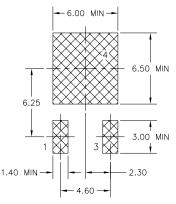
10.00 ±0.20

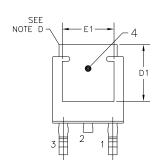
Dimensions in Millimeters

Physical Dimension (Continued)

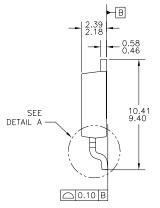
D-PAK

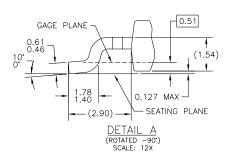












- NOTES: UNLESS OTHERWISE SPECIFIED

 A) ALL DIMENSIONS ARE IN MILLIMETERS.

 B) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA & AB, DATED NOV. 1999.

 C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

 D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.

 E) DIMENSIONS L3.D.E1&D1 TABLE:

			OPTION AA	OPTION AB	
		L3	0.89-1.27	1.52-2.03	
		D	5.97-6.22	5.33-5.59	
		E1	4.32 MIN	3.81 MIN	
		D1	5.21 MIN	4.57 MIN	
F)	PF	RESE	NCE OF TE	RIMMED CEI	NTER

LEAD IS OPTIONAL.

Dimensions in Millimeters





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Definition of Forms					
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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
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